Apr./2008	MITSUBISHI SEMICONDUTOR <gaas fet=""></gaas>			
	SUPER	LOW NOISE InGaAs HEMT (4pin flat lead package)		
DESCRIPTION The MGF4934CM super-low noise HEMT Transistor) is designed for use in S to Ku ban The 4pin flat lead package is small-thin size performance.	(High Electron Mobility d amplifiers. e, and offers high cost	Outline Drawing		
FEATURES Low noise figure @ f=12GHz NFmin. = 0.50dB (Typ.) High associated gain @ f=12GHz Gs = 13.0dB (Typ.)		Fig.1		
	MITSUBISHI F Not to be reprodu	Ced or disclosed		
S to Ku band low noise amplifiers	without permission by Mitsubishi Electric			
QUALITY GRADE GG				
RECOMMENDED BIAS CONDITION $V_{DS}=2V$ , $I_D=10mA$	S			
ORDERING INFORMATION Tape & reel 3000pcs/reel	Keep S Mitsubishi Electric Corp semiconductor product possibility that trouble r may lead to personal in consideration to safety measure such as (I) pla	Safety first in your circuit designs! boration puts the maximum effort into making s better and more reliable, but there is always the may occur with them. Trouble with semiconductors njury, fire or property damage. Remember to give due when making your circuit designs, with appropriate accement of substitutive, auxiliary circuits, (ii) use of		

#### ABSOLUTE MAXIMUM RATINGS (Ta=25°C) Symbol Parameter Unit Ratings Gate to drain voltage $V_{\text{GDO}}$ -3 V V<sub>GSO</sub> Gate to source voltage -3 V $I_D$ Drain current IDSS mΑ ΡT mW Total power dissipation 50 T<sub>ch</sub> Channel temperature 125 °C T<sub>stg</sub> Storage temperature °C -55 to +125

### ELECTRICAL CHARACTERISTICS (Ta=25°C )

Symbol	Parameter	Test conditions	Limits			Unit
			MIN.	TYP.	MAX	
V <sub>(BR)GDO</sub>	Gate to drain breakdown voltage	I <sub>G</sub> =-10μΑ	-3.5			V
I <sub>GSS</sub>	Gate to source leakage current	V <sub>GS</sub> =-2V,V <sub>DS</sub> =0V			50	μA
I <sub>DSS</sub>	Saturated drain current	V <sub>GS</sub> =0V,V <sub>DS</sub> =2V	12		60	mA
V <sub>GS(off)</sub>	Gate to source cut-off voltage	V <sub>DS</sub> =2V,I <sub>D</sub> =500μA	-0.1		-1.5	V
Gs	Associated gain	VDS=2V,	11.5	13.0		dB
NFmin.	Minimum noise figure	I <sub>D</sub> =10mA,f=12GHz		0.50	0.75	dB

non-flammable material or (iii) prevention against any malfunction or mishap.

# MITSUBISHI SEMICONDUTOR <GaAs FET> MGF4934CM

SUPER LOW NOISE InGaAs HEMT (4pin flat lead package)



(GD-30)

SUPER LOW NOISE InGaAs HEMT (4pin flat lead package)

### TYPICAL CHARACTERISTICS (Ta=25°C)



SUPER LOW NOISE InGaAs HEMT (4pin flat lead package)

### S PARAMETERS

(VDS=2V,ID=10mA,Ta=room temperature) S21 S12 S22 S11 Freq. (GHz) (mag) (ang) (mag) (ang) (mag) (ang) (mag) (ang) 1 0.990 -16.3 5.156 158.7 0.032 79.5 0.758 -9.2 2 -<u>30.1</u> 4.971 145.3 0.037 70.2 0.728 -<u>19.5</u> 0.985 -29.9 3 4.787 0.930 -43.8 131.9 0.042 60.9 0.698 -57.5 4.602 51.6 -40.3 4 0.860 118.5 0.047 0.668 5 4.470 103.9 43.4 -50.0 0.802 -72.1 0.055 0.634 6 -87.3 4.343 <u>89.3</u> 0.061 36.2 0.594 -59.5 0.737 7 0.668 -103.24.212 74.6 0.066 29.7 0.555 -68.9 8 0.599 -119.64.042 60.2 0.070 24.0 0.514 -78.3 9 0.533 -136.5 3.852 46.4 0.072 18.9 0.473 -87.3 -1<u>52.0</u> 10 0.072 0.440 -95.2 0.477 3.672 33.9 17.3 11 0.442 -168.03.537 21.6 0.076 17.1 0.418 -104.2 12 0.421 175.7 3.429 9.5 0.083 17.2 0.400 -114.1 13 0.406 159.0 3.331 -2.4 0.090 15.9 0.383 -124.4 -14.1 14 0.405 142.8 3.264 0.099 14.1 0.375 -135.6 15 0.425 126.5 3.236 -26.9 0.115 10.1 0.379 -150.33.214 16 0.460 -40.8 0.137 5.3 110.8 0.403 -168.9 17 0.503 94.9 3.149 -54.5 0.156 -2.2 0.417 172.6 -11.2 18 80.2 0.448 0.547 3.058 -68.3 0.175 153.5

### Noise Parameter

(V <sub>DS</sub> =2V,I <sub>D</sub> =10mA, Ta=room temperature))								
Freq.	NFmin	Гopt		Горt Ri		Rn		
(GHz)	(dB)	(mag)	(ang)	(Ω)				
1	0.25	0.97	8.2	17.5				
2	0.25	0.97	14.5	15.4				
3	0.26	0.94	22.9	14.0				
4	0.29	0.91	30.2	12.5				
5	0.30	0.88	40.2	11.0				
6	0.32	0.82	48.2	9.5				
7	0.35	0.74	61.2	8.0				
8	0.37	0.65	75.5	6.5				
9	0.39	0.57	91.3	5.0				
10	0.42	0.49	108.4	3.6				
11	0.46	0.44	127.0	2.6				
12	0.49	0.39	146.9	1.9				
13	0.53	0.34	168.2	1.8				
14	0.57	0.30	-169.1	2.0				



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